

CORRIGENDUM:2

Date: 09/02/2026

Tender ID: 2026_IITK_894526_1

Tender Title: Supply, Installation, and Commissioning of Electron Microscope (Dual Beam FIBSEM System with Accessories)

Tender Ref. No.: PI/ACMS/RD/2025-26/NPG/NC-10

(1) Following changes have been made to the tender document for the purpose of the Supply, Installation, and Commissioning of the Electron Microscope (Dual Beam FIBSEM System with Accessories):

1: Main equipment: Dual Beam FIB-SEM

S. No.	Description	Specifications
1.1	System requirements	1.1.4. The offered FIB-SEM system shall support correlative analysis with X-ray based non-destructive inspection system (XRM / Micro-CT)
1.17.	Correlative microscopy Feature	1.17.1. Include and describe any capability to establish correlation with X-ray based non-destructive inspection system (XRM / Micro-CT)) 1.17.2. Include and describe software-based correlation between X-ray data and FIB-SEM coordinates, enabling precise navigation to user-defined regions of interest (ROI) identified during prior X-ray inspection. 1.17.3. The solution shall allow single or multiple ROIs to be transferred from the X-ray dataset to the FIB-SEM environment and accurately mapped onto the physical sample. 1.17.4. The correlation accuracy shall be sufficient to enable targeted cross-sectioning, lamella preparation, or site-specific failure analysis with minimal trial and error material removal. 1.17.5. The workflow shall enable seamless handover from nondestructive X-ray inspection to destructive FIB-SEM analysis, thereby reducing sample damage, analysis time, and operator dependency. 1.17.6. The vendor shall provide complete hardware, software, and workflow support, including installation, configuration, and user training for X-ray-to-FIB-SEM correlative analysis. Also confirm that the offered system supports future software upgrades for correlative workflows without requiring replacement of core hardware components.

(2) Under term and conditions please include: “Any variations can be described by the bidder in their compliance sheet.”

(3) Change the resolution from 0.9 to 1.0 nm at page no. 29 under 1.6.1

All bidders are requested to consider the above-mentioned incorporated changes made in the specifications in the technical bid and quote accordingly and provide a separate price bifurcation for the optional accessories. Thank You

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